

ABSTRACT

Provided are a compound having excellent low dielectric properties, a curable resin composition, and a cured product of the same. This compound is represented by formula (1). In formula (1), R₁'s, which exist in a quantity of more than one, each independently represent
 5 a hydrogen atom or a hydrocarbon group having 1-5 carbon atoms. R₂'s, which exist in a quantity of more than one, each independently represent a hydrocarbon group represented by formula (a). X represents a structure represented by formula (c)-(f). l's, which exist in a quantity of more than one, each independently represent an integer of 1-4. m's, which exist in a quantity of more than one, each independently represent an integer of 0-3 and the average
 10 value m_{ave} of m's satisfies $0 < m_{ave} \leq 3$. n represents the number of repeats, and the average n_{ave} of n's satisfies $0.05 \leq n_{ave} \leq 20$. In formula (a), * represents the site of binding to a fluorene structure in formula (1). R₃ represents a hydrogen atom or a hydrocarbon group having 1-5 carbon atoms. k represents an integer of 1-5. In formulae (c)-(f), * represents the site of binding to a fluorene structure in formula (1). R₄'s, which exist in a quantity of more
 15 than one, each independently represent a hydrogen atom or a hydrocarbon group having 1-5 carbon atoms. p's, which exist in a quantity of more than one, each independently represent an integer of 1-4, and q's, which exist in a quantity of more than one, each independently represent an integer of 1-3.